

PHB66NQ03LT

N-channel TrenchMOS logic level FET

Rev. 07 — 30 January 2009

Product data sheet

1. Product profile

1.1 General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product is designed and qualified for use in computing, communications, consumer and industrial applications only.

1.2 Features and benefits

- Low conduction losses due to low on-state resistance
- Suitable for logic level gate drive sources

1.3 Applications

- DC-to-DC convertors
- General purpose switching

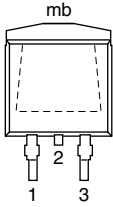
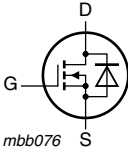
1.4 Quick reference data

Table 1. Quick reference

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25\text{ °C}$; $T_j \leq 175\text{ °C}$	-	-	25	V
I_D	drain current	$T_{mb} = 25\text{ °C}$; $V_{GS} = 10\text{ V}$	-	-	66	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$; see Figure 2	-	-	93	W
Dynamic characteristics						
Q_{GD}	gate-drain charge	$V_{GS} = 5\text{ V}$; $I_D = 50\text{ A}$; $V_{DS} = 15\text{ V}$; $T_j = 25\text{ °C}$; see Figure 11	-	3.6	-	nC
Static characteristics						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}$; $I_D = 25\text{ A}$; $T_j = 25\text{ °C}$; see Figure 9 ; see Figure 10	-	9.1	10.5	mΩ

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 SOT404 (D2PAK)	 <i>mbb076</i>
2	D	drain [1]		
3	S	source		
mb	D	mounting base; connected to drain		

[1] It is not possible to make a connection to pin 2.

3. Ordering information

Table 3. Ordering information

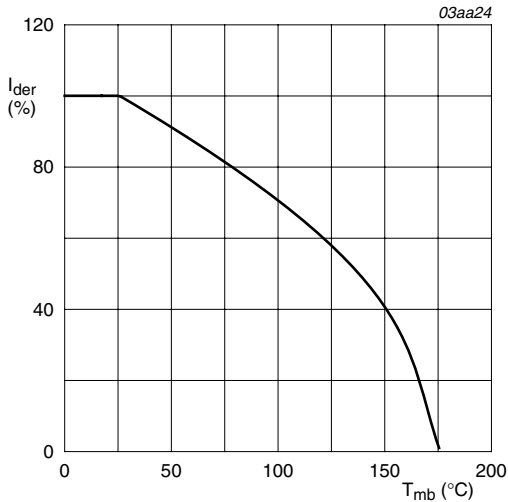
Type number	Package		Version
	Name	Description	
PHB66NQ03LT	D2PAK	plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)	SOT404

4. Limiting values

Table 4. Limiting values

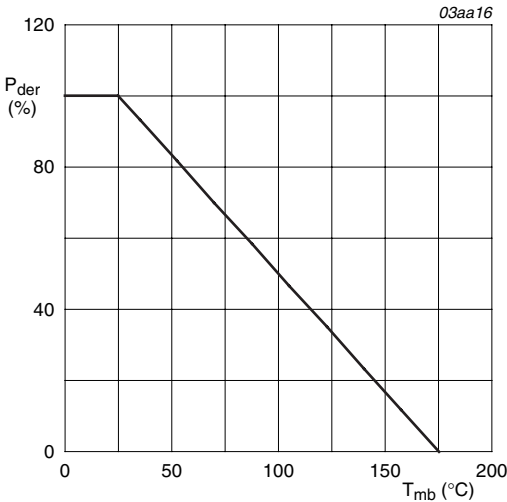
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25\text{ }^{\circ}\text{C}$; $T_j \leq 175\text{ }^{\circ}\text{C}$	-	25	V
V_{DGR}	drain-gate voltage	$T_j \geq 25\text{ }^{\circ}\text{C}$; $T_j \leq 175\text{ }^{\circ}\text{C}$; $R_{GS} = 20\text{ k}\Omega$	-	25	V
V_{GS}	gate-source voltage		-20	20	V
I_D	drain current	$V_{GS} = 10\text{ V}$; $T_{mb} = 100\text{ }^{\circ}\text{C}$	-	45	A
		$V_{GS} = 5\text{ V}$; $T_{mb} = 100\text{ }^{\circ}\text{C}$; see Figure 1	-	40	A
		$V_{GS} = 5\text{ V}$; $T_{mb} = 25\text{ }^{\circ}\text{C}$; see Figure 1 ; see Figure 3	-	57	A
		$V_{GS} = 10\text{ V}$; $T_{mb} = 25\text{ }^{\circ}\text{C}$	-	66	A
I_{DM}	peak drain current	$t_p \leq 10\text{ }\mu\text{s}$; pulsed; $T_{mb} = 25\text{ }^{\circ}\text{C}$; see Figure 3	-	228	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ }^{\circ}\text{C}$; see Figure 2	-	93	W
T_{stg}	storage temperature		-55	175	$^{\circ}\text{C}$
T_j	junction temperature		-55	175	$^{\circ}\text{C}$
Source-drain diode					
I_S	source current	$T_{mb} = 25\text{ }^{\circ}\text{C}$	-	57	A
I_{SM}	peak source current	$t_p \leq 10\text{ }\mu\text{s}$; pulsed; $T_{mb} = 25\text{ }^{\circ}\text{C}$	-	228	A
Avalanche ruggedness					
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$V_{GS} = 10\text{ V}$; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; $I_D = 43\text{ A}$; $V_{sup} \leq 25\text{ V}$; unclamped; $t_p = 0.15\text{ ms}$; $R_{GS} = 50\text{ }\Omega$	-	90	mJ



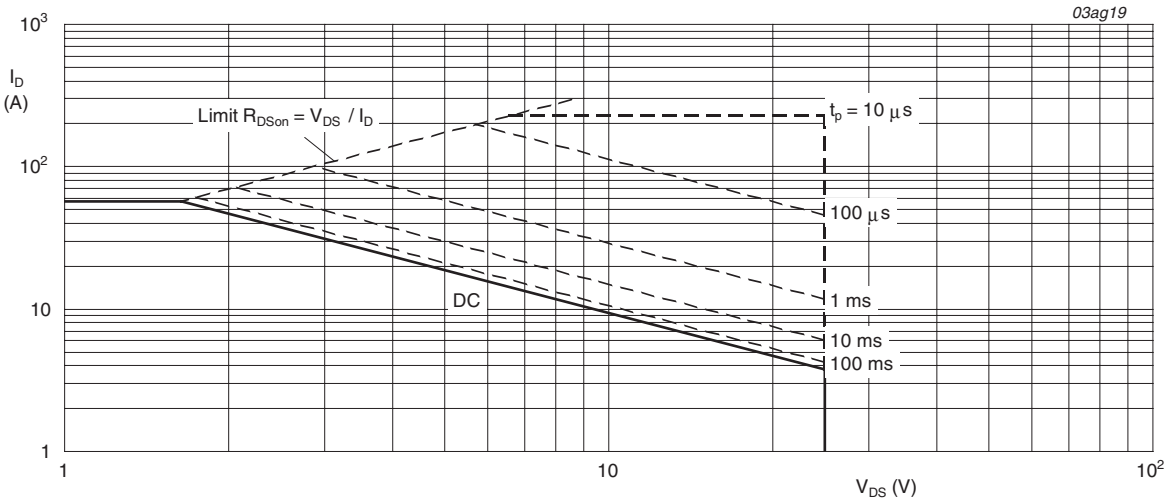
$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

Fig 1. Normalized continuous drain current as a function of mounting base temperature



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized total power dissipation as a function of mounting base temperature



$$T_{mb} = 25^{\circ}C; I_{DM} \text{ is single pulse}; V_{GS} = 5V$$

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	mounted on a printed-circuit board; minimum footprint; vertical in still air	-	50	-	K/W
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	-	1.6	K/W

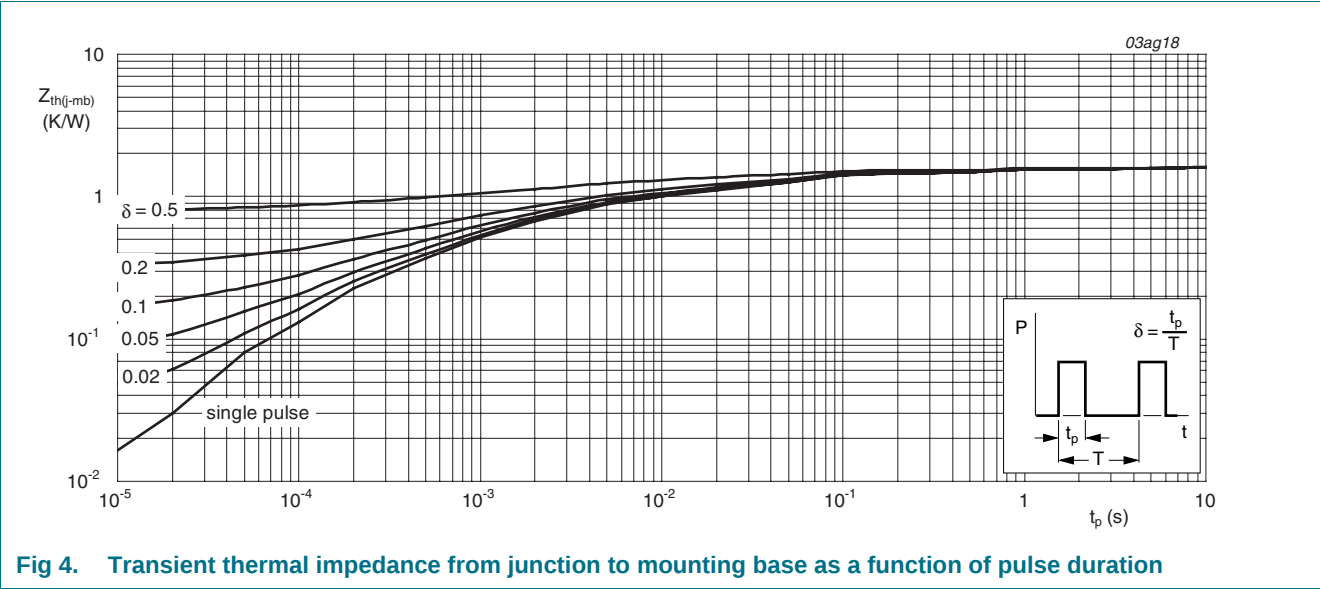


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V _{(BR)DSS}	drain-source breakdown voltage	I _D = 250 μA; V _{GS} = 0 V; T _j = -55 °C	22	-	-	V
		I _D = 250 μA; V _{GS} = 0 V; T _j = 25 °C	25	-	-	V
V _{GS(th)}	gate-source threshold voltage	I _D = 1 mA; V _{DS} = V _{GS} ; T _j = -55 °C; see Figure 7 ; see Figure 8	-	-	2.2	V
		I _D = 1 mA; V _{DS} = V _{GS} ; T _j = 175 °C; see Figure 7 ; see Figure 8	0.5	-	-	V
		I _D = 1 mA; V _{DS} = V _{GS} ; T _j = 25 °C; see Figure 7 ; see Figure 8	1	1.5	2	V
I _{DSS}	drain leakage current	V _{DS} = 25 V; V _{GS} = 0 V; T _j = 25 °C	-	-	10	μA
		V _{DS} = 25 V; V _{GS} = 0 V; T _j = 175 °C	-	-	500	μA
I _{GSS}	gate leakage current	V _{GS} = 15 V; V _{DS} = 0 V; T _j = 25 °C	-	10	100	nA
		V _{GS} = -15 V; V _{DS} = 0 V; T _j = 25 °C	-	10	100	nA
R _{DSon}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 25 A; T _j = 175 °C; see Figure 9 ; see Figure 10	-	16.4	18.9	mΩ
		V _{GS} = 5 V; I _D = 25 A; T _j = 25 °C; see Figure 9 ; see Figure 10	-	11.2	13.6	mΩ
		V _{GS} = 10 V; I _D = 25 A; T _j = 25 °C; see Figure 9 ; see Figure 10	-	9.1	10.5	mΩ
Dynamic characteristics						
Q _{G(tot)}	total gate charge	I _D = 50 A; V _{DS} = 15 V; V _{GS} = 5 V; T _j = 25 °C; see Figure 11	-	12	-	nC
Q _{GS}	gate-source charge		-	4.5	-	nC
Q _{GD}	gate-drain charge		-	3.6	-	nC
C _{iss}	input capacitance	V _{DS} = 25 V; V _{GS} = 0 V; f = 1 MHz; T _j = 25 °C; see Figure 12	-	860	-	pF
C _{oss}	output capacitance		-	330	-	pF
C _{rss}	reverse transfer capacitance		-	145	-	pF
t _{d(on)}	turn-on delay time	V _{DS} = 15 V; R _L = 0.6 Ω; V _{GS} = 5 V; R _{G(ext)} = 5.6 Ω; T _j = 25 °C	-	15	25	ns
t _r	rise time		-	90	135	ns
t _{d(off)}	turn-off delay time		-	25	40	ns
t _f	fall time		-	25	40	ns
Source-drain diode						
V _{SD}	source-drain voltage	I _S = 25 A; V _{GS} = 0 V; T _j = 25 °C; see Figure 13	-	0.95	1.2	V
t _{rr}	reverse recovery time	I _S = 10 A; dI _S /dt = -100 A/μs; V _{GS} = 0 V; V _{DS} = 25 V; T _j = 25 °C	-	32	-	ns
Q _r	recovered charge		-	20	-	nC

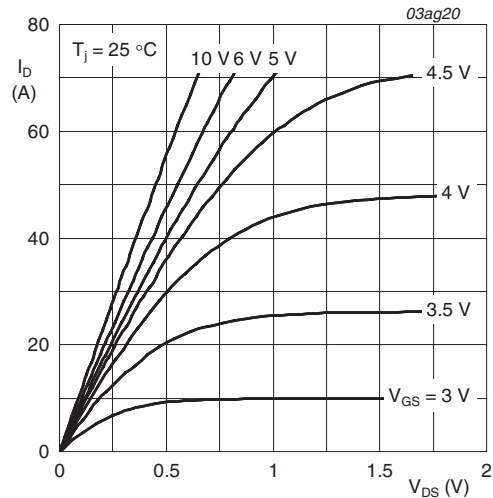


Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values

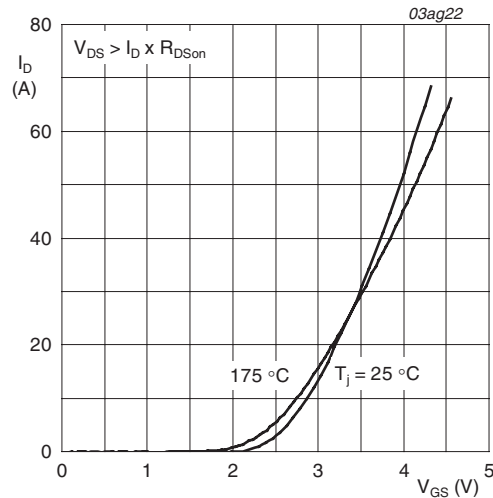


Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values

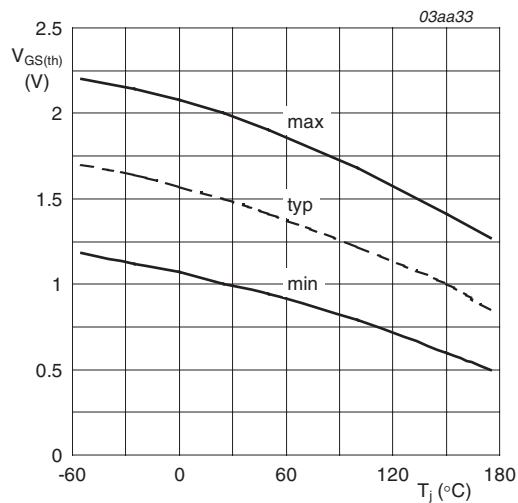


Fig 7. Gate-source threshold voltage as a function of junction temperature

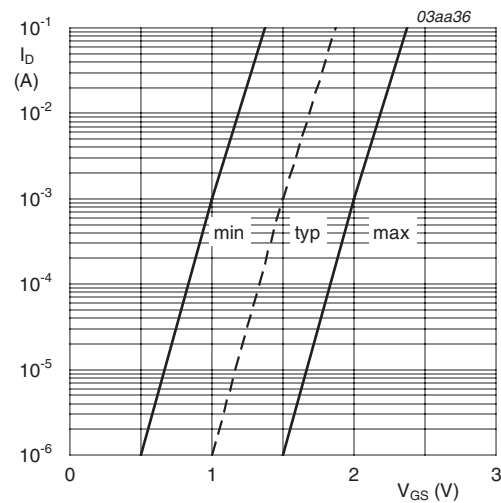


Fig 8. Sub-threshold drain current as a function of gate-source voltage

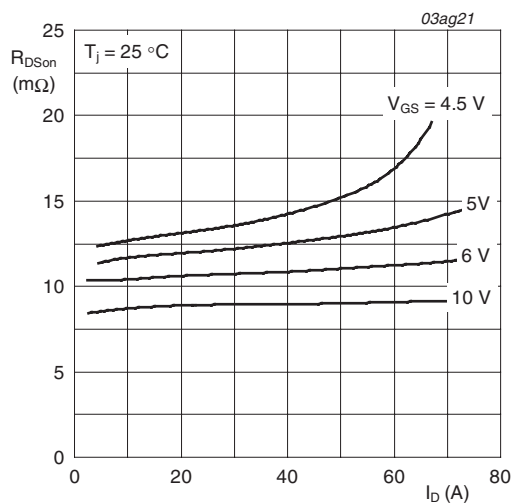
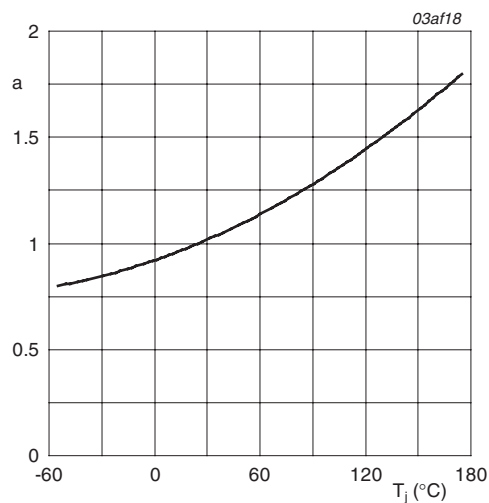

 $T_j = 25^\circ\text{C}$

Fig 9. Drain-source on-state resistance as a function of drain current; typical values



$$a = \frac{R_{DS(on)}}{R_{DS(on)(25^\circ\text{C})}}$$

Fig 10. Normalized drain-source on-state resistance factor as a function of junction temperature

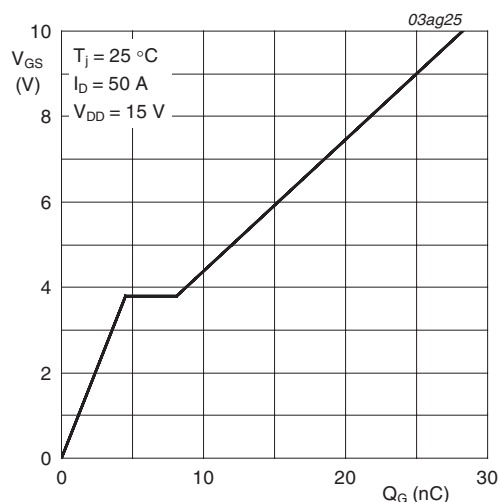

 $I_D = 50\text{A}; V_{DS} = 15\text{V}$

Fig 11. Gate-source voltage as a function of gate charge; typical values

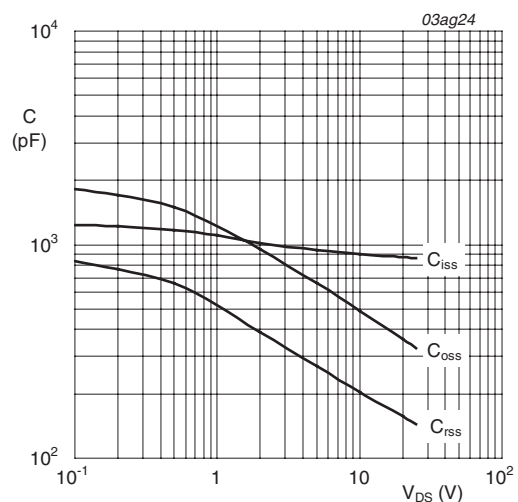
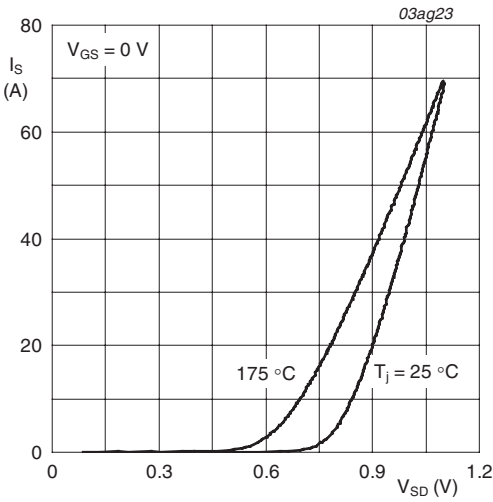

 $V_{GS} = 0\text{V}; f = 1\text{MHz}$

Fig 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$T_j = 25^\circ\text{C}$ and $175^\circ\text{C}; V_{GS} = 0\text{ V}$

Fig 13. Source current as a function of source-drain voltage; typical values

7. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)

SOT404

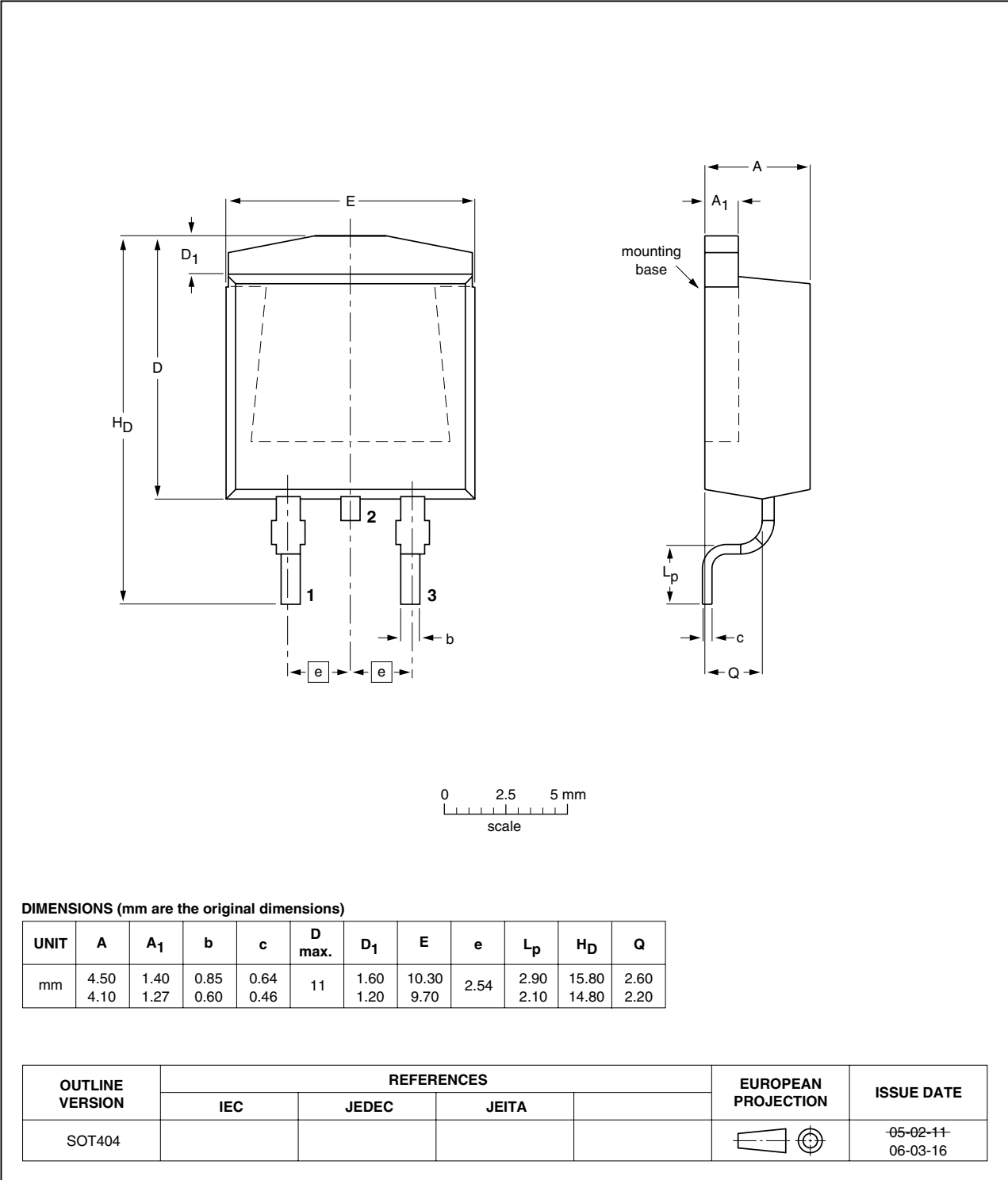


Fig 14. Package outline SOT404 (D2PAK)

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PHB66NQ03LT_7	20090130	Product data sheet	-	PHB_PHD66NQ03LT_6
Modifications: - The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. - Legal texts have been adapted to the new company name where appropriate.				
PHB_PHD66NQ03LT_6 (9397 750 13429)	20040802	Product data sheet	-	PHP_PHB_PHD66NQ03LT_5
PHP_PHB_PHD66NQ03LT_5 (9397 750 13107)	20040415	Product data sheet	-	PHP_PHB_PHD66NQ03LT_4
PHP_PHB_PHD66NQ03LT_4 (9397 750 10158)	20020909	Product data sheet	-	PHP_PHB_PHD66NQ03LT_3
PHP_PHB_PHD66NQ03LT_3 (9397 750 09284)	20020312	Product data sheet	-	PHP_PHB_PHD66NQ03LT_2
PHP_PHB_PHD66NQ03LT_2 (9397 750 09119)	20011210	Product data sheet	-	PHP_PHB_PHD66NQ03LT_1
PHP_PHB_PHD66NQ03LT_1 (9397 750 08725)	20011012	Product data sheet	-	-

9. Legal information

9.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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